

## Abstract of the Disclosure

Disclosed is a method for fabricating Surface Acoustic Wave filter packages using a package sheet having an outline pattern and anti-bur holes and a package sheet used therein.

5 In the package sheet for a Surface Acoustic Wave filter package, an outline pattern is formed along outer peripheries of predetermined areas to be mounted with a plurality of SAW filter chips. The outline pattern is contacted with a metal shield

10 layer formed on the SAW filter chips and a predetermined region of the package sheet. Circular anti-bur holes cover the corners of the areas to be mounted with the SAW filter chips and are intersected by cutting lines functioning as reference lines for cutting the sheet into a plurality of SAW filter packages.

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